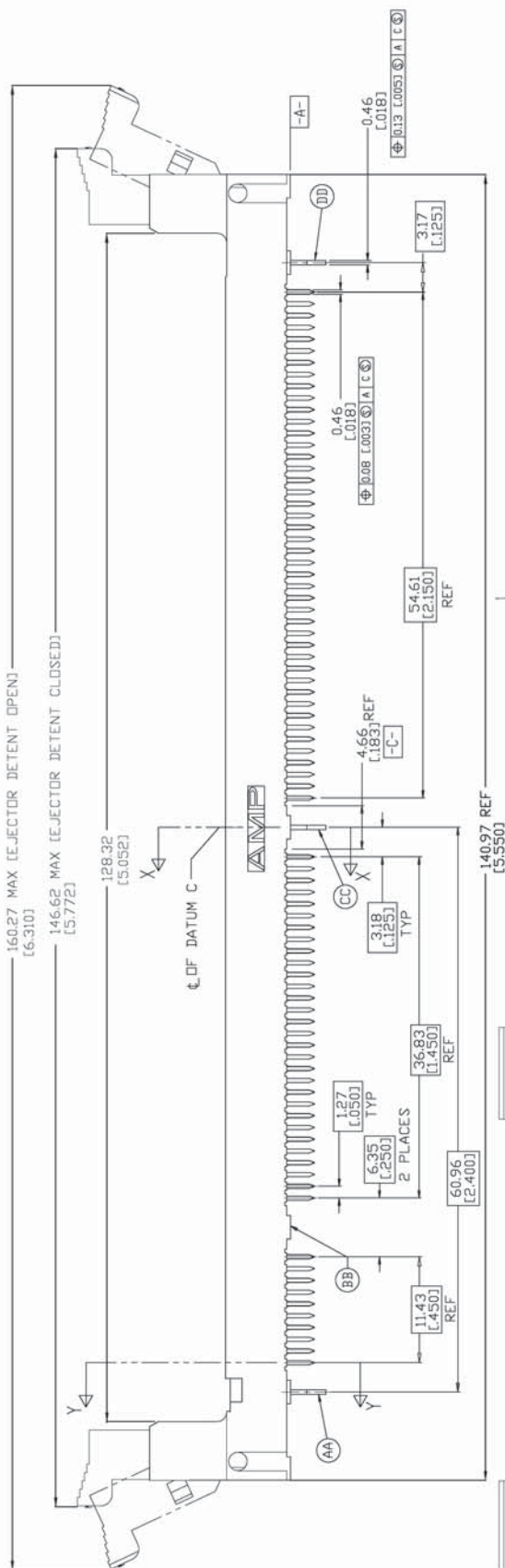
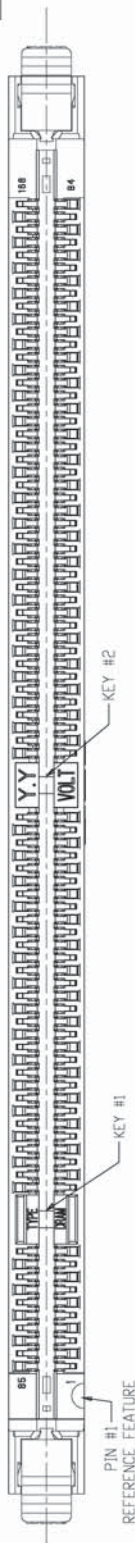




△ MATERIAL
HOUSING: GLASS FILLED HIGH TEMPERATURE NYLON, COLOR: BLACK.
CONTACT: PHOS. BRONZE, CS1100, TEMPER H06.
RETENTION POST: STAINLESS STEEL, AMP SPEC 100-309.

FINISH

CONTACT:
NICKEL PLATE ALL OVER 0.00127mm - 0.0019mm [0.00050 IN - 0.00075 IN] THICK.

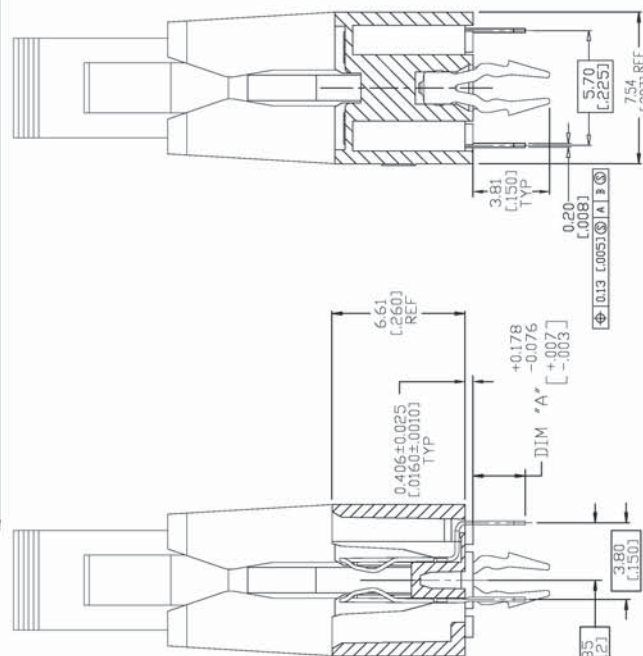
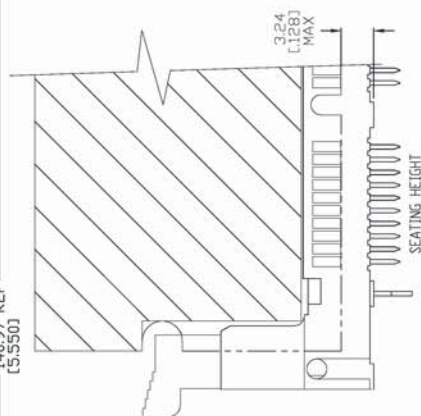
PER AMP SPEC 112-25-2.

GOLD PLATE IN INTERFACE AREA PER AMP SPEC 112-162-5.

SEE TABLE FOR MIN. THICKNESS.
 MATTE TIN PLATE IN SOLDER TAIL AREA 0.00381mm - 0.00635mm [0.00150 IN - 0.00250 IN] THICK.
 PER AMP SPEC 112-65-1.

EXTRACTOR MATERIAL: GLASS FILLED HIGH TEMPERATURE NYLON CTP NR: NATURAL OFF-WHITE

EXTENDED ABSTRACTS

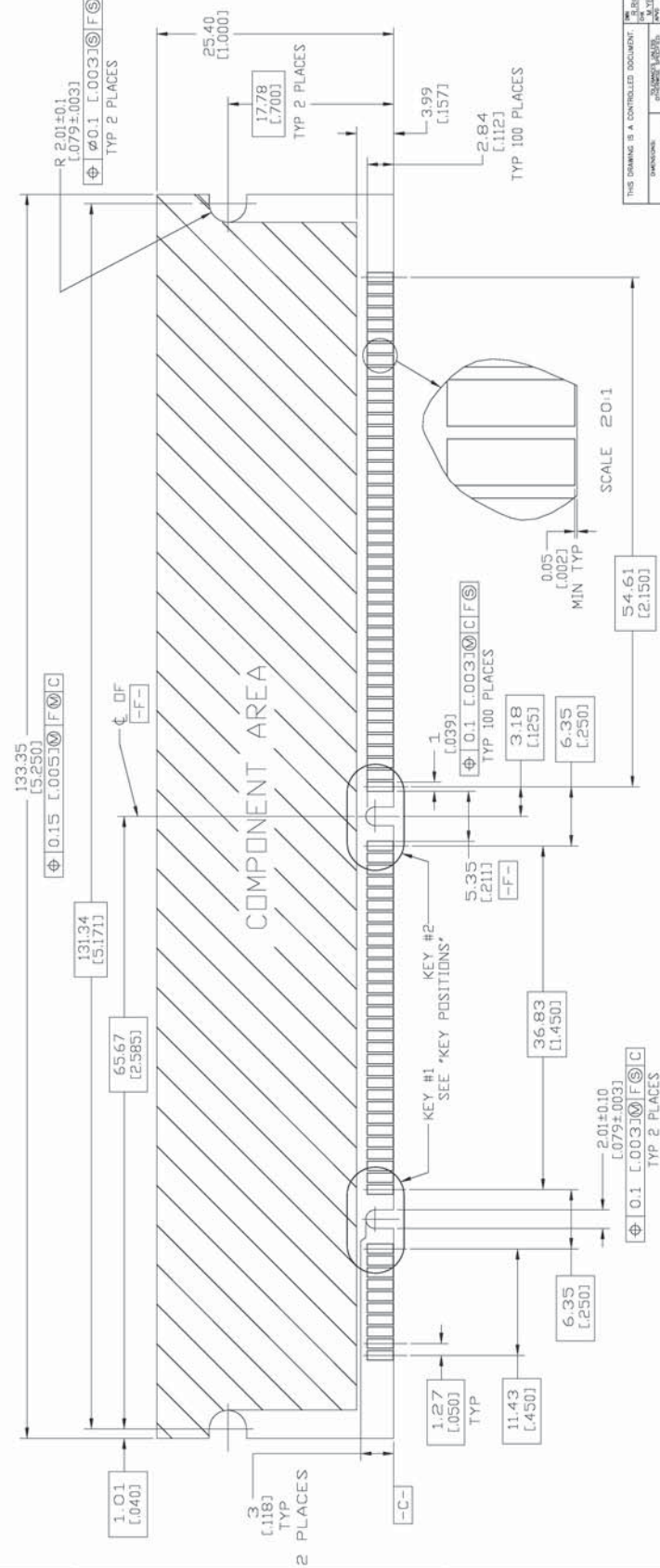
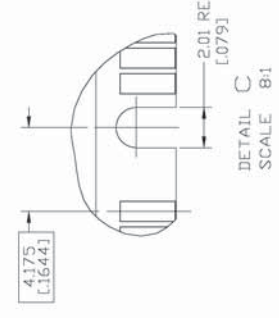
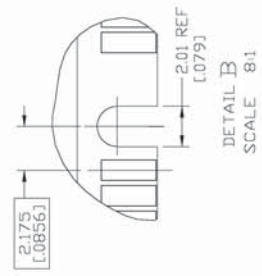
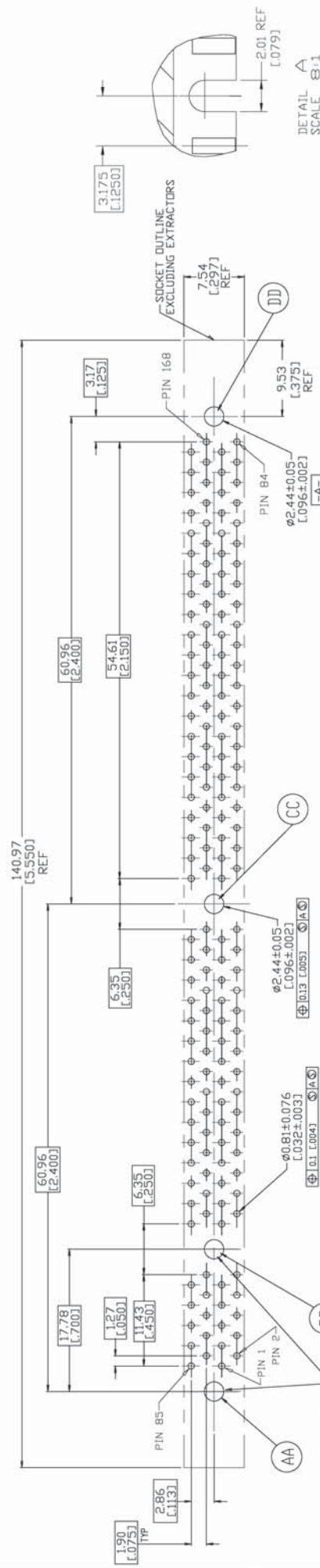


SECTION Y-Y
CIRCUITS 1 AND 51
SCALE 8:1

SECTION SCALE X-X 8:1

DIM 'A'	RETENTION POST	KEY #1	KEY #2	EXTRACTOR	GOLD PLATE	DESCRIPTION	PART NUMBER
4.06 [160]	BB-CC-3D	DETAIL-C	DETAIL-A		0.00076mm L000030 IN	NON-BUFFERED DRAM, 3.3 VOLT, POST-PLATED CONTACTS	1-5390169-3
4.06 [160]	AA-CC-3D	DETAIL-C	DETAIL-A		0.00076mm L000030 IN	NON-BUFFERED DRAM, 3.3 VOLT, POST-PLATED CONTACTS	1-5390169-2
4.06 [160]	AA-CC-3D	DETAIL-C	DETAIL-A		0.00076mm L000030 IN	NON-BUFFERED DRAM, 3.3 VOLT, POST-PLATED CONTACTS	1-5390169-1

[illegible]



"KEY POSITIONS"

[illegible]

RECOMMENDED MODULE LAYOUT
SEE JEDEC SPEC. MD-161 FOR COMPLETE MODULE DETAILS,
1.27±0.10[.050±.004] THICK ACROSS PADS